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# Specification

(Reference)

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

Style: RAC10 2D,RAC10 4D,RAC16 4D, RAC16 8D

# **RoHS COMPLIANCE ITEM**

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Issue Dept.: Research & Development Department Hokkaido Research Center

Drawing No: RAC-K-HTS-0001

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

Page: 1/15

/13

#### 1. Scope

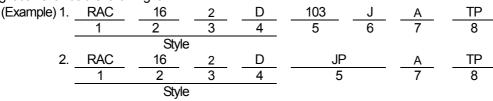
1.1 This specification covers the detail requirements for fixed chip resistors networks; rectangular type, style of RAC10 2D,10 4D,16 4D, 16 8D.

#### 1.2 Applicable documents

JIS C 5201–1: 1998, JIS C 5201–9: 2006, JIS C 5201–9–1: 2006 IEC60115–1: 1999, IEC60115–9: 2003, IEC60115–9–1: 2003 EIAJ RC–2129–2000.

#### 2. Classification

Type designation shall be the following form.



1 Fixed chip resistors networks; rectangular type

2 Size

3 Number of element

4 Circuits

5 Rated resistance Example;  $103 \rightarrow 10$ k $\Omega$ , Chip jumper: JP

6 Tolerance on rated resistance

7 Terminal style

8 Packaging form 1. Scope

#### 3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style

Style		Terminations style	Rated element dissipation (W)	Rated network dissipation (W)	Temperature coefficient of resistance ( 10 <sup>-6</sup> / °C)	Rated resistance range(Ω)	Preferred number series for resistors	Tolerance on rated resistance
RAC10	2D 4D	С	0.063	0.125	±200	10~1.0M	E24	J(±5%)
RAC16	4D	С	0.063	0.25	±200	10~1.0M	E24	F(±1%) J(±5%)
	8D	С	0.063	0.25	±200	10~1.0M	E24	J(±5%)

Style	)	Limiting element voltage(V)	Isolation voltage(V)	Number of element	Circuit networks	Category temperature range(°C)
RAC10	2D	25	50	2	D	
	4D			4	J D	<i>–</i> 55∼+125
RAC16	4D	50	100	4	(Independence type)	-55~±125
100010	8D	25	100	8		

Note. Rated current of chip jumper: 1(A)

Note. Resistance value of chip jumper:  $50m\Omega$  max.

#### 3.2 Climatic category

55/125/56 Lower category temperature –55 °C

Upper category temperature +125 °C

Duration of the damp heat, steady state test 56days

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 2/15

#### 3.3 Stability class

5% Limits for change of resistance:

-for long-term tests  $\pm$ (5%+0.1Ω) Chip jumper: 50 mΩ max. -for short-term tests  $\pm$ (1%+0.05Ω) Chip jumper: 50 mΩ max.

#### 3.4 Derating

The derated values of dissipation (or current rating in case of chip jumper) at temperature in excess of 70 °C shall be as indicated by the following curve.

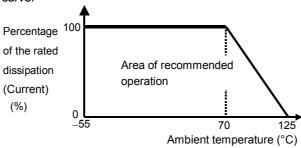


Figure-1Derating curve

#### 3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E : Rated voltage (V)

P : Rated dissipation (W)

R : Rated resistance (
$$\Omega$$
)

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

#### 4. Packaging form

The standard packaging form shall be in accordance with Table-2.

#### Table-2

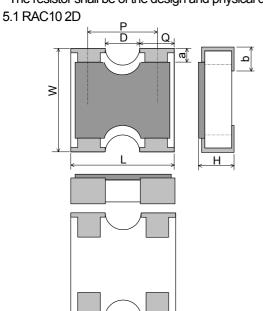
Symbol	Packaging form		Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	RAC10 2D, 4D, RAC16 4D, 8D
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	RAC10 2D, 4D
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RAC16 4D, 8D

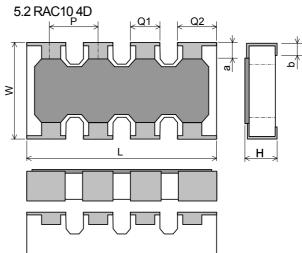
Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

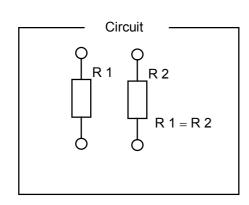
RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 3/15

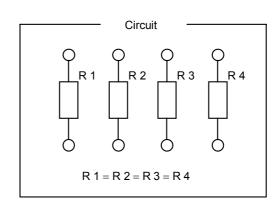
#### 5. Dimensions

The resistor shall be of the design and physical dimensions in accordance with below.









Figure–2 Figure–3

Table–3 Unit: mm

Style	Terminations style	Country of origin	L	W	Н	Q or Q₁	$*Q_2$
RAC10 2D	С	Malaysia,	1.0±0.05	1.0±0.05	0.35±0.05	0.33±0.10	
		China	1.0±0.1	1.0±0.1	0.35±0.10	0.34±0.05	
RAC10 4D	С	Malaysia,	2.0±0.1	1.0±0.1	0.35±0.05	0.35±0.10	0.45±0.10
		China	2.0±0.1	1.0±0.1	0.45±0.10	0.3±0.05	0.4±0.1

Style	Country of origin	D	а	h	*P
Otyle	,	D	а	D	*[
RAC10 2D	Malaysia,	0.34±0.10	0.15±0.10	$0.25^{+0.05}_{-0.10}$	0.65
1001020	China		0.2±0.15	0.25±0.17	0.65
RAC10 4D	Malaysia,		0.15±0.10	0.25±0.10	0.5
NAC 10 4D	China		0.2±0.1	0.25±0.10	0.5

\*Reference

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 4/15

#### 5.3 RAC16 4D

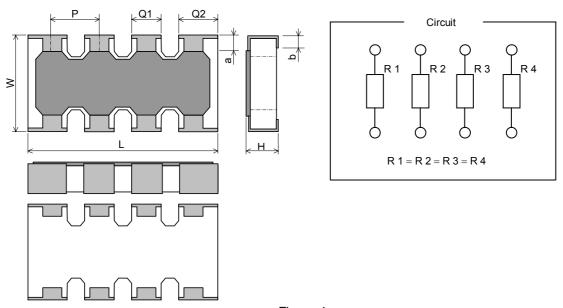


Figure 4

			TUDIC T				Offic. ITHIT
Style	Terminations style	Country of origin	L	W	Н	Q <sub>1</sub>	а
DAC16 4D	C	Malaysia,	3.2±0.1	1.6±0.1	0.5±0.1	0.4±0.15	0.3±0.2
RAC16 4D	C	China	3.2±0.1	1.6±0.1	0.5±0.1	0.4±0.1	0.3±0.1

Style	Country of origin	b	$*Q_2$	*P
RAC16 4D	Malaysia,	0.25±0.15	0.6±0.15	0.8
KAC 10 4D	China	0.3±0.2	0.6±0.1	8.0

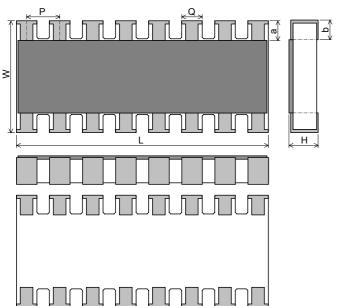
\*Reference

Unit: mm

FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 5/15

#### 5.4 RAC16 8D



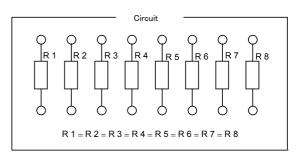


Figure-5

Table-5

Unit: mm

Style	Terminations style	Country of origin	L	W	Н	Q	а
RAC168D	С	China	3.8±0.1	1.6±0.1	0.45±0.10	0.3±0.1	0.3±0.1

\*Reference

Style	Country of origin	b	*P
RAC168D	China	0.3±0.1	0.5±0.1

#### 5.2 Net weight (Reference)

Style	Terminations style	Net weight(mg)
RAC10 2D	С	1.1
RAC104D	С	2.1
RAC164D	С	7
RAC16 8D	С	8.3

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 6/15

#### 6. Marking

The Rated resistance of RAC10 2D should not be marked.

#### 6.1 For the resistors

The rated resistance shall be marked in 3 digits (E24) and marked on over coat side.

Marking	example	Contents	Application
Malaysia	China	Contents	Дрисацоп
123	123	$12\times10^3 \ [\Omega] \rightarrow 12 \ [k\Omega]$	RAC104D
D123	123	12×10 <sup>3</sup> [Ω] → 12 [kΩ]	RAC164D
	123	12×10 <sup>3</sup> [Ω] → 12 [kΩ]	RAC168D

## 6.2 For the Jumper Chip

Marking	example	Contents	Application	
Malaysia	China	Contents		
	000	JP	RAC104D	
DO	000	JP	RAC164D	
	000	JP	RAC168D	

#### 7. Performance

- 7.1 The standard condition for tests shall be in accordance with Sub-clause 4. 2, JIS C 5201–1: 1998.
- 7.2 The performance shall be satisfied in Table-6.

Table-6(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements				
1	Visual examination	Sub-clause 4. 4. 1 Checked by visual examination.	As in 4. 4. 1 The marking shall be legible, as checked by visual examination.				
2	Dimension	Sub-clause 4. 4. 2	As specified in sub clause5.1 of this specification.				
	Resistance	Sub-clause 4. 5	As in 4. 5. 2 The resistance value shall correspond with the rated resistance taking into account the specified tolerance. Chip jumper: 50 mΩ max.				
3	Voltage proof	Sub-clause 4. 7 Method: 4. 6. 1. 4(See Figure-8) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s ± 5 s Insulation resistance Test voltage: Insulation voltage Duration: 1 min.	No breakdown or flash over $R \ge 1 \ G \ \Omega$				
4	Solderability	Sub-clause 4. 17 Without ageing Flux: The resistors shall be immersed in a non-activated soldering flux for 2s. Bath temperature: 235 °C ± 5 °C Immersion time: 2 s ± 0.5 s	As in 4. 17. 4. 5 The terminations shall be covered with a smooth and bright solder coating.				



Drawing No: RAC-K-HTS-0001 /13

FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE Title:

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 7/15

Table-6(2)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements
5	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
	0.004	Test substrate: Figure–6	
	Overload (in the manufact of atota)	Sub-clause 4. 13	
	(in the mounted state)	The applied voltage shall be 2.5 times the	
		rated voltage or twice the limiting element	
		voltage, whichever is the less severe.	
		Duration: 2 s Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
		1 Nesistatice	Chip jumper: 50 m $\Omega$ max.
	Solvent resistance of the	Sub-clause 4. 30	Legible marking
	marking	Solvent: 2–propanol	3 3
		Solvent temperature: 23°C±5°C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–7	
	Bound strength of the end	Sub-clause 4. 33	
	face plating	Bent value: 3 mm	AD (1/40/10.050)
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Final measurements	Out. stans 4 00 0	Chip jumper: 50 mΩ max. No visible damage
	T I I I I I I I I I I I I I I I I I I I	Sub-clause 4. 33. 6 Visual examination	NO VISIDIE dal l'iage
7	Resistance to soldering heat	Sub-clause 4. 18	
′	Tresistance to soldening heat	Solder temperature: 260°C±5°C	
		Immersion time: 10s±0.5s	
		Visual examination	As in 4. 18. 3. 4
		Visual Statistical	No sign of damage such as cracks.
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
			Chip jumper: $50 \text{ m}\Omega$ max.
	Component solvent	Sub-clause 4.29	
	resistance	Solvent: 2-propanol	
		Solvent temperature: 23°C±5°C	
		Method 2	
		Recovery: 48 h	Nie vielkie deusees
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
			Chip jumper: $50 \mathrm{m}\Omega$ max.



Drawing No: RAC-K-HTS-0001 /13

Page:

8/15

FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE Title: RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

Table-6(3)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements
8	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-6	
	Adhesion	Sub-clause 4. 32	
		Force: 5 N	
		Duration: 10s±1s	No visible demons
	Rapid change temperature	Visual examination	No visible damage
	Rapid Change temperature	Sub-clause 4.19	
		Lower category temperature : -55 °C	
		Upper category temperature : +125 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles.	No visible damage
		Visual examination	$\Delta R \le \pm (1\% + 0.05\Omega)$
		Resistance	Chip jumper: 50 m $\Omega$ max.
9	Climatic sequence	Sub-clause 4. 23	omp jampon oo maa max
	-Dry heat	Sub-clause 4. 23. 2	
		Test temperature: +125 °C	
		Duration: 16 h	
	–Damp heat, cycle	Sub-clause 4. 23. 3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4. 23. 4	
		Test temperature–55 °C	
		Duration: 2h	
	–Damp heat, cycle	Sub-clause 4. 23. 6	
	(12+12hourcycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4. 23. 7	
		The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is	
		the smaller.	
		Duration: 1 min.	No visible damage
		Visual examination	$\Delta R \le \pm (5\% + 0.1\Omega)$
		Resistance	Chip jumper: 50 m $\Omega$ max.



FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE Title: RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

Page: 9/15

Table-6(4)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements
10	Mounting  Endurance at 70 °C	Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure–6 Sub-clause 4. 25. 1 Ambient temperature: 70°C±2°C Duration: 1000 h The voltage shall be applied in cycles of 1. 5 h on and 0. 5 h off. The applied voltage shall be the rated voltage or the limiting element voltage whichever is the smaller. Examination at 48 h , 500 h and 1000 h:	
		Visual examination Resistance	No visible damage $\Delta R \le \pm (5\% + 0.1\Omega)$ Chip jumper: 50 m $\Omega$ max.
11	Mounting  Variation of resistance with temperature	Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure–6 Sub-clause 4. 8 -55 °C / +20 °C +20 °C / +125°C	As in Table–1
12	Mounting  Damp heat, steady state	Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure–6 Sub-clause 4. 24 Ambient temperature: 40°C±2°C Relative humidity: 93 +2/3 % a) 1st group: without voltage applied. b) 2nd group: The d. c. voltage shall be applied continuously. The voltage shall be accordance with Sub-clause 4. 24. 2.1 b). without polarizing voltage [4. 24. 2. 1, c)] Visual examination Resistance	No visible damage Legible marking $\Delta R \le \pm (5\%+0.1\Omega)$ Chip jumper: 50 m $\Omega$ max.

Page:

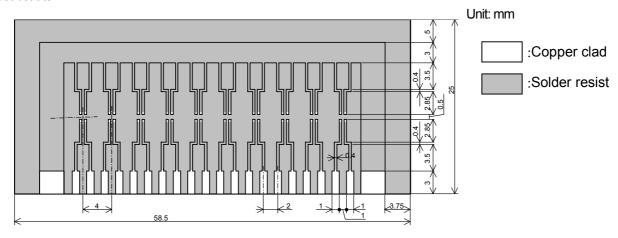
10/15

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

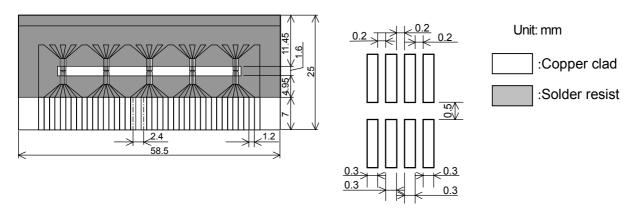
Table-6(5)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements					
13	Dimensions (detail)	Sub-clause 4. 4. 3	As spe	in cifica	Sub-clause tion	5.1	of	this
	Mounting	Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure-6						
	Endurance at upper category temperature	Sub-clause 4. 25. 3 Ambient temperature:125°C±2°C Duration: 1000 h Examination at 48 h, 500 h and 1000 h:						
		Visual examination Resistance	ΔR	≤ <b>±</b> (	e damage 5%+0.1Ω) per: 50 mΩ m	ax.		

#### 8. Test substrate



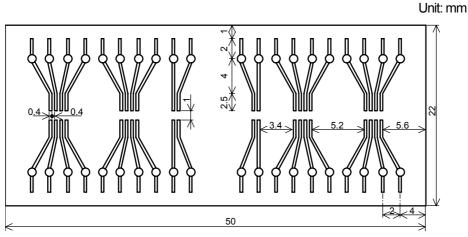
# RAC10 2D TEST SUBSTRATE



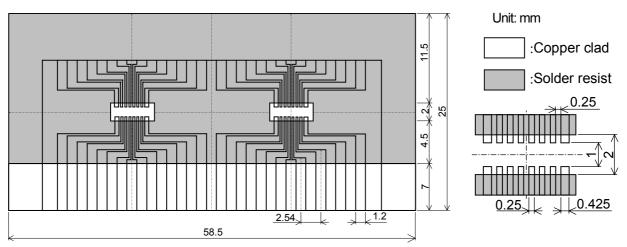
**RAC10 4D TEST SUBSTRATE** 

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

Page: 11/15

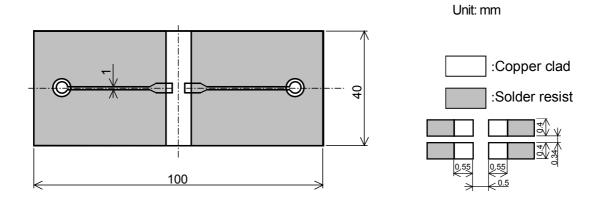


**RAC16 4D TEST SUBSTRATE** 



**RAC16 8D TEST SUBSTRATE** 

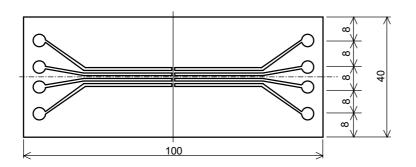
- Remark 1). Material: Epoxide woven glass
  Thickness: 1. 6mm Thickness of copper clad: 0.035mm
  - In the case of connection by connector, the connecting terminals are gold plated.
     However, the plating is not necessary when the connection is made by soldering.
     Figure–6

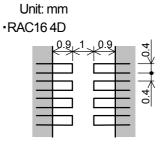


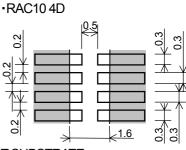
RAC10 2D BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D

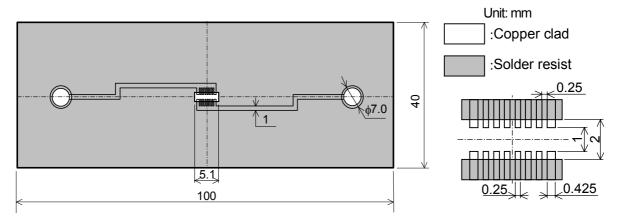
Page: 12/15





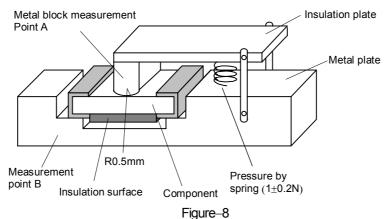


RAC10 4D, 16 4D BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE



RAC16 8D TERMINAL STRENGTH TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass
Thickness: 1.6mm Thickness of copper clad: 0.035mm
Figure–7



Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 13/15

#### 9. Taping

- 9.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7200B: 2003
- 9.2 Taping dimensions
- 9.2.1 RAC10 2D, RAC10 4D (Paper taping, 8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-8 and Table-7.

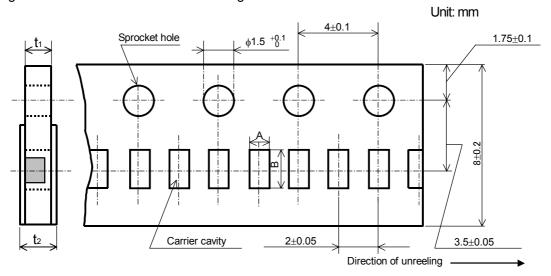


Figure-9 Table-7 Unit: mm В t<sub>1</sub> t<sub>2</sub> +0.05  $1.15 \begin{array}{l} +0.05 \\ -0.10 \end{array}$  $1.15 \begin{array}{l} +0.05 \\ -0.10 \end{array}$ 0.4 0.5max. 1.2±0.1

 $0.4 \pm 0.1$ 

2.2±0.1

#### 9.2.2 RAC16 4D, RAC16 8D (Paper taping, 8mm width, 4mm pitches)

Style

RAC102D

RAC104D

Taping dimensions shall be in accordance with Figure-10 and Table-8.

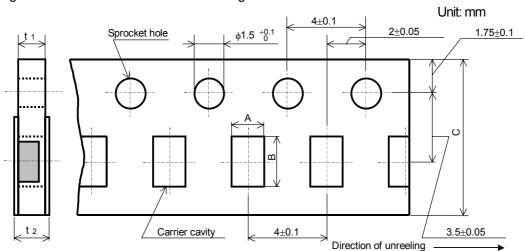
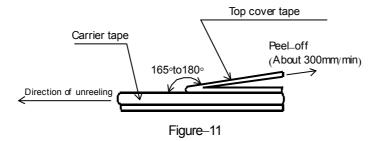


Figure-10 Table-8 Unit: mm С t 1 Style Α В t<sub>2</sub> RAC164D 1.9±0.15 3.6±0.2 8.0±0.2 0.6±0.1 0.8max. RAC168D 1.9±0.15 4.1±0.15  $8.0\pm0.3$ 

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE
RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 14/15

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure-11.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
  The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.
- 9). The direction of resistor shall be taped as Figure-12.



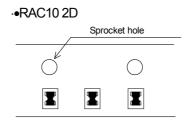


Figure-12

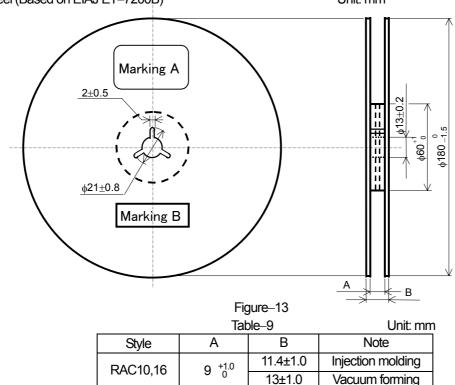
Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE

RAC10 2D, RAC10 4D, RAC16 4D, RAC16 8D Page: 15/15

#### 9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–13 and Table–9. Plastic reel (Based on EIAJ ET–7200B)

Unit: mm



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

#### 9.4 Leader and trailer tape.

(Example)

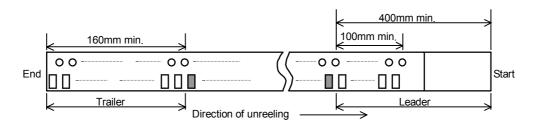


Figure-14

#### 10. Marking on package

The label of a minimum package shall be legibly marked with follows.

#### 10.1 Marking A

- (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Terminal style, Packaging form)
- (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 10.2 Marking B (KAMAYA Control label)

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# Kamaya:

RAC164D510JCTP RAC164D1000FCTP RAC164D4701FCTP RAC164D1101FCTP

# Walsin:

RAC164D473JCTF	RAC104D221JCTH	RAC164D220JCTF	RAC104D102JCTH	H RAC164D302JCTP
RAC104D330JCTH	RAC164D512JCTP	RAC164D333JCTP	RAC104D472JCTH	RAC164D681JCTP
RAC164D103JCTP	RAC164D680JCTP	RAC164D202JCTP	RAC164D201JCTP	RAC104D474JCTH
RAC164D101JCTP	RAC104D332JCTH	RAC104D103JCTH	RAC164D153JCTP	RAC104D390JCTH
RAC164D132JCTP	RAC164D102JCTP	RAC164D330JCTP	RAC164D161JCTP	RAC164D513JCTP
RAC164D360JCTP	RAC164D104JCTP	RAC164D100JCTP	RAC104D822JCTH	RAC104D223JCTH
RAC164D392JCTP	RAC104D151JCTH	RAC104D201JCTH	RAC164D332JCTP	RAC104D150JCTH
RAC164D152JCTP	RAC164D151JCTP	RAC104D152JCTH	RAC104D104JCTH	RAC104D473JCTH
RAC164D303JCTP	RAC104D304JCTH	RAC164D154JCTP	RAC104D220JCTH	RAC104D100JCTH
RAC104D101JCTH	RAC164D472JCTP	RAC104D470JCTH	RAC164D821JCTP	RAC164D393JCTP
RAC164D331JCTP	RAC164D131JCTP			

## Other:

RAC102D471JCTH RAC164D111FCTP RAC164DJPCTP RAC164D101FCTP RAC102D220JCTH RAC102D104JCTH RAC104DJPCTH RAC102D361JCTH RAC164D472FCTP RAC102D330JCTH